



**Customer :** Texas Instruments  
**Part Num :** TSW3085  
**Part Rev :** C

**Job Name :** TI\_TSW3085  
**Engineer :** David Gorden  
**Facility :** Toronto

Layer	Calc Thickness	Primary Stack	Description
Layer - 1	0.0005 0.0020		Taiyo 4000-MP 1/2oz Sig (Std Plt)
	0.0076		370H
Layer - 2	0.0006 0.0080		1/2oz P/G
Layer - 3	0.0006 0.0074		370H
Layer - 4	0.0006 0.0080		1/2oz P/G
Layer - 5	0.0006 0.0074		370H
Layer - 6	0.0006 0.0080		1/2oz Mix
Layer - 7	0.0006 0.0076		370H
Layer - 8	0.0020 0.0005		1/2oz Sig (Std Plt) Taiyo 4000-MP

Requirement	Req. Thickness	Tol +	Tol -	Calc Thick
Incl. Plating & Mask	0.0620	0.0062	0.0062	0.0626
Incl. Mask over Laminate	0.0580	0.0058	0.0058	0.0586
Incl. Plating	0.0610	0.0061	0.0061	0.0616
After Lamination	0.0582	0.0029	0.0029	0.0588
Over Laminate	0.0570	0.0057	0.0057	0.0576

Impedance Type	Layer	Design	Actual	Pitch	Plane	Target	Tol (ohms)	Predict
1  Surface MS	L1	0.0120	0.0125	-	-	50	5.0	49.74
	-	-	-	-	L2			
2  EC Microstrip	L1	0.0060	0.0057	0.0110	-	100	10.0	99.68
	-	0.0060	0.0057	-	L2			
3  EC Stripline	L3	-	0.0048	0.0110	L2	100	10.0	99.52
	-	-	0.0048	-	L4			
4  Surface MS	L8	0.0120	0.0125	-	L7	50	5.0	49.74
	-	-	-	-	-			
5  EC Microstrip	L8	0.0060	0.0057	0.0110	L7	100	10.0	99.68
	-	0.0060	0.0057	-	-			